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Thomas Tank Engine Videos

"Lucy Gallant" on Vide w/ Jane Wyman & Charlt Heston DVD VHS IIS



Merriam-Webster



3 entries found for **etch**. To select an entry, click on it.



Main Entry: ¹etch *
Pronunciation: 'ech

Function: verb

Etymology: Dutch etsen, from German ätzen to etch, corrode, from Old High German azzen to feed; akin to Old High German ezzan to eat -- more at EAT

Date: 1634 transitive senses

1 a: to produce (as a pattern or design) on a hard material by eating into the material's surface (as by acid or laser beam) b: to subject to such etching

2: to delineate or impress clearly <scenes etched in our minds> <pain was etched on his features>

intransitive senses: to practice etching

- etch-er noun

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772 Solder composition:

This subclass is indented under subclass 741. Subject matter wherein the specific contact or lead material is a solder composition (i.e., a metal or metallic alloy that melts at relatively low temperatures).

 Note. Solder is normally used to join metals with higher melting points than the solder composition. Def 53 PACKAGE MAKING Page: 129

404 With solder or wax sealing:

This subclass is indented under subclass 403. Methods including the step or steps of applying and fusing or merely fusing a heat sensitive bonding agent in conjunction with the step of closing.

- Note. The fusing of the material either seals and secures a separate closure onto a receptacle or serves as a closure itself for a vent-like opening.
- (2) Note. The term "solder" is here used, loosely, to include any metallic or nonmetallic heat sensitive bonding agent.

289.1 Solder:

This subclass is indented under subclass 285.1. Subject matter wherein the members are bonded by a melted metal (usually a tin alloy) cement.

263 With solder:

This subclass is indented under subclass 262. Subject matter wherein the conductive material is a readily meltable metal or alloy that produces a bond at a junction of two metal surfaces.

57 Having means to apply solid solder:

This subclass is indented under subclass 56. Apparatus wherein means are provided for assembling an easily fusible metal, e.g., solder, with the end closure while said fusible metal is in the solid state.

743 Solder connection:

This subclass is indented under subclass 736. Subject matter wherein at least part of the printed circuit board's component(s) is interconnected with a readily meltable metal or alloy that produces a bond at a junction of two metal surfaces.

Release layer utilized:

468

This subclass is indented under subclass 467. Subject matter wherein a layer on the support is used to facilitate the separation of the material to be transferred.

41.8 Release layer:

This subclass is indented under subclass 40.1. Subject matter wherein the layer or component contains a bond inhibiting material or parting material used to prevent adhesion between lamina in areas that might otherwise bond in the absence of the material.

With outer strippable or release layer:

202

This subclass is indented under subclass 201. Product in which one of the adjacent layers lies on the outermost surface of the web or sheet and is removable from the web or sheet or is so made as to prevent adhesion to a surface in contact therewith.